PCB CLEANER - concentrated

SYS-CLEAN BC1.0 is a water-based cleaning medium for flux removal of printed circuit boards, ceramic substrates, lead frames and power modules. **SYS-CLEAN BC1.0** is well suited to prepare surfaces for subsequent wire bonding and coating processes.
SYS-CLEAN BC1.0 is specific additivated to protect sensitive surfaces from unwanted chemical reactions.
The cleaner can be used in spray, immersion and ultrasonic cleaning systems.

Application

Pollution	Suitability
Low solid flux	✓✓
Colophonium flux	✓✓
Water soluble flux	✓✓
Solder paste	✓✓
SMT adhesives	✓

Application Parameters

Parameter	
Application temperature	40 - 60°C
Cleaning duration approx	10 - 30 min.
Rinsing	DI-Water
Drying	convection/ compressed air
Application concentration	15 – 30%

Specifications SYS-CLEAN BC1.0 is supplied as concentrate.	
Density	1,03 g/cm³
Boiling point	~100°C
Flashpoint	>90°C
pH value	10,5

SYS-CLEAN BC1.0

Advantages: SYS-CLEAN BC1.0 is configured extremely gently while providing good cleaning performance. Due to the high loading capacity with best filterability, a particularly cost-effective process is guaranteed.

Type of application: Spray in air / spray under immersion / ultrasonic

Purity Standards: the following standards are achieved by cleaning PCBs with **SYS-CLEAN BC1.0**:

- solderability acc J-STD 003
- Ionic purity and resin purity acc J-STD 001
- Visual purity acc IPC-A-610
- Surface resistivity IPC-TM 650 and DIN 32513

Safety: Please note the information in the MSDS.

Disposal: If required, we will take back used medium and undertake the disposal for you.

Availability: SYS-CLEAN BC1.0 is available in pack sizes of 25 or 200 liters.

ALL COMPONENTS REACH COMPLIANT
Registration, Evaluation and Authorisation of Chemicals

The product is free of questionable ingredients in accordance with the SIN & SVHC lists

RoHS · WEEE · COMPLIANT

100% compliant with the EU RoHS directive 1 & 2, WEEE